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SPH1642HT5H-1

SPH1642HT5H-1 Rev B Datasheet

Wide Bandwidth, Low Noise, Precision Top Port SiSonic™ Microphone

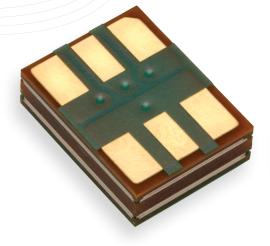
The SPH1642HT5H-1 is a miniature, high-performance, low power, top port silicon microphone. Using Knowles' proven high performance SiSonic™ MEMS technology, the SPH1642HT5H-1 consists of an acoustic sensor, a low noise input buffer, and an output amplifier. These devices are suitable for applications such as cellphones, smart phones, laptop computers, sensors, digital still cameras, portable music recorders, and other portable electronic devices where excellent wideband audio performance and RF immunity are required.

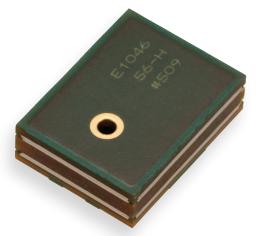
Product Features:

- Flat Frequency Response
- MaxRF Protection
- Sensitivity Matching
- Ultra-Stable Performance
- Standard SMD Reflow
- Omnidirectional
- Small Size

Typical Applications

- Portable electronics
- Cellphones
- Laptop Computers
- Tablets
- Portable Music Recorders
- · Digital Still Cameras





Absolute Maximum Ratings

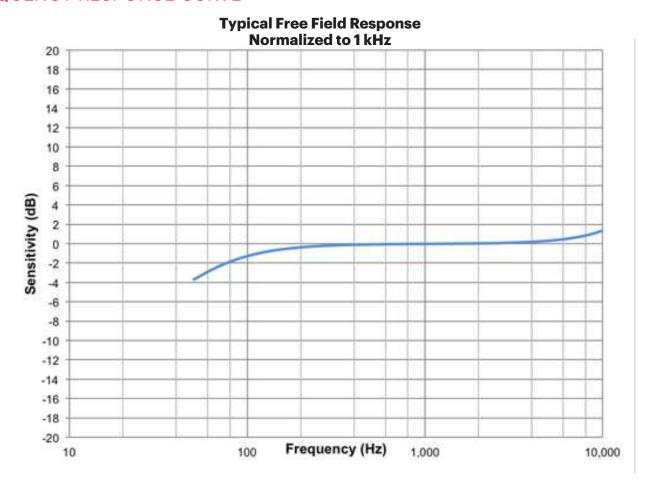
Parameter	Absolute Maximum Rating	Units
Vdd to Ground	-0.3, +5.0	V
OUT to Ground	-0.3, +5.0	V
Input Current	±5	mA
Temperature	-40 to +100	°C

Stresses exceeding these "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation at these or any other conditions beyond those indicated under "Acoustic & Electrical Specifications" is not implied. Exposure beyond those indicated under "Acoustic & Electrical Specifications" for extended periods may affect device reliability.

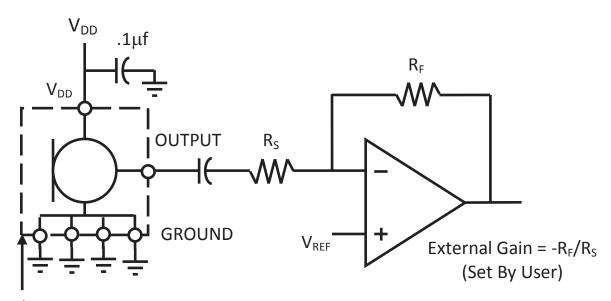
Parameter	Symbol	Conditions	Min.	Тур.	Max	Units
Supply Voltage ¹	VDD		1.5	-	3.6	V
0	IDD	VDD = 1.8V	-	117	130	μΑ
Supply Current ¹		VDD = 3.6V		132	185	
Sensitivity ¹	S	94 dB SPL @ 1 kHz	-39	-38	-37	dBV/Pa
Signal to Noise Ratio	SNR	94 dB SPL @ 1 kHz, A-weighted	-	65	-	dB(A)
Total Harmonic Distortion	THD	94 dB SPL @ 1 kHz, S = Typ, Rload > 3 k Ohms	-	.25	-	%
Acoustic Overload Point	AOP	10% THD @ 1 kHz, S = Typ, VDD = 3.6V, Rload > 3 k Ohms	-	124	-	dB SPL
Power Supply Rejection Ratio	PSRR	200mVpp sinewave @ 1 kHz, VDD = 1.8V	-	77	-	dB
Power Supply Rejection	PSR	100 mVpp 1/8 duty cycle rectangular waveform @ 217 Hz, A-weighted, 20kHz BW	-	-102	-	dBV(A)
DC Output		VDD = 1.8V	-	1.3	-	V
Output Impedance	ZOUT	@ 1 kHz	-	-	500	Ohms
Directivity				Omnidir	ectional	
Polarity		Increasing sound pressure	Inc	reasing o	utput volt	age

^{1100%} Tested

FREQUENCY RESPONSE CURVE



Interface Circuit



Dotted Section

Represents

. SiSonicTM

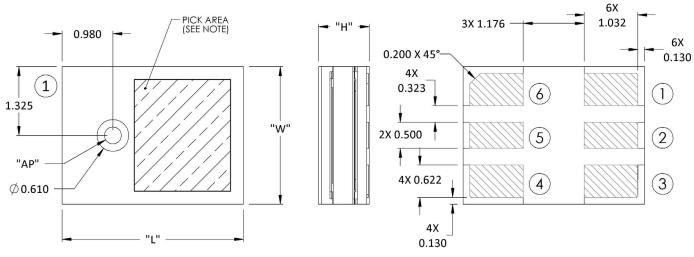
Microphone

Notes: All Ground pins must be connected to ground.

Capacitors near the microphone should not contain Class 2 dielectrics.

 $Detailed information on acoustic, mechanical, and system integration can be found in the latest SiSonic \\ ^{\mathtt{M}} Design Guide application note. \\$

Mechanical Specifications



Item	Dimension	Tolerance
Length (L)	3.50	±0.10
Width (W)	2.65	±0.10
Height (H)	1.00	±0.10
Acoustic Port (AP)	Ø0.325	±0.050

Pin#	Pin Name	Туре	Description
1	GROUND	Power	Ground
2	GROUND	Power	Ground
3	GROUND	Power	Ground
4	OUTPUT	Signal	Output Signal
5	GROUND	Power	Ground
6	VDD	Power	Power Supply

Notes: Pick Area only extends to 0.25 mm of any edge or hole unless otherwise specified.

Dimensions are in millimeters unless otherwise specified.

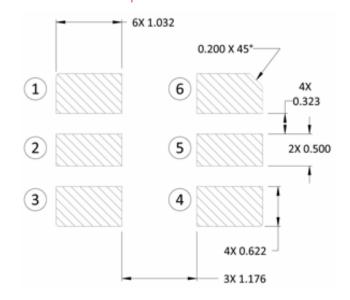


Tolerance is ±0.15mm unless otherwise specified.

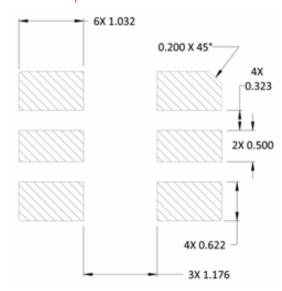
Detailed information on AP size considerations can be found in the latest <u>SiSonic™ Design Guide</u> application note.

Further optimizations based on application should be performed.

Example Land Pattern

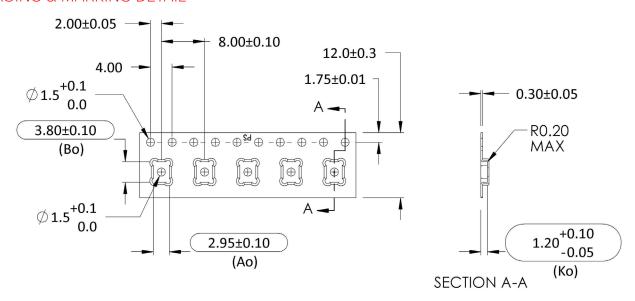


Example Solder Stencil Pattern



Mechanical Specifications (cont'd)

PACKAGING & MARKING DETAIL



Model Number	Suffix	Reel Diameter	Quantity Per Reel
SPH1642HT5H-1	8	13″	5,900

Alpha Character A:

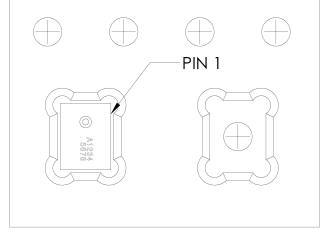
"S": Knowles SiSonicTM Production

"E": Knowles Engineering Samples

"P": Knowles Prototype Samples

"12345678":

Unique Job Identification Number for product traceability



Notes:

Dimensions are in millimeters unless otherwise specified.

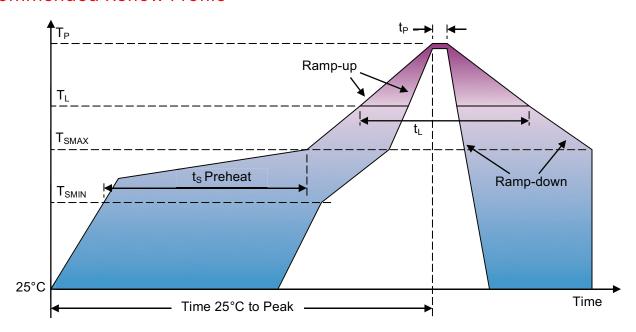
Vacuum pickup only in the pick area indicated in Mechanical Specifications $\,$

Tape & reel per EIA-481.

Labels applied directly to reel and external package.

Shelf life: Twelve (12) months when devices are to be stored in factory supplied, unopened ESD moisture sensitive bag under maximum environmental conditions of 30°C, 70% R.H.

Recommended Reflow Profile



Profile Feature	Pb-Free
Average Ramp-up rate (Tsmax to Tp)	3°C/second max.
Preheat Temperature Min (Tsmin) Temperature Max (Tsmax) Time (Tsmin to Tsmax) (ts)	150°C 200°C 60-180 seconds
Time maintained above:	217°C 60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _P)	20-40 seconds
Ramp-down rate (TP to TSMAX)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max

Notes:

Based on IPC/JDEC J-STD-020 Revision C.

All temperatures refer to topside of the package, measured on the package body surface

Additional Notes

- (A) MSL (moisture sensitivity level) Class 1.
- (B) Maximum of 3 reflow cycles is recommended.
- (C) In order to minimize device damage:
 - Do not board wash or clean after the reflow process.
 - Do not brush board with or without solvents after the reflow process.
 - Do not directly expose to ultrasonic processing, welding, or cleaning.
 - Do not insert any object in port hole of device at any time.
 - Do not apply over 30 psi of air pressure into the port hole.
 - Do not pull a vacuum over port hole of the microphone.
 - Do not apply a vacuum when repacking into sealed bags at a rate faster than 0.5 atm/sec.

Materials Statement

Meets the requirements of the European RoHS directive 2011/65/EC as amended.

Meets the requirements of the industry standard IEC 61249-2-21:2003 for halogenated substances and Knowles Green Materials Standards Policy section on Halogen-Free.

Ozone depleting substances are not used in the product or the processes used to make the product, including compounds listed in Annex A, B, and C of the "Montreal Protocol on Substances That Deplete the Ozone Layer."

Reliability Specifications

Test	Description
Reflow	5 reflow cycles with peak temperature of +260°C
High Temperature Storage	+105°C environment for 1,000 hours (IEC 68-2-2 Test Ba)
Low Temperature Storage	-40°C environment for 1,000 hours (IEC 68-2-1 Test Aa)
High Temperature Bias	+105°C environment while under bias for 1,000 hours (IEC 68-2-2 Test Ba)
Low Temperature Bias	-40°C environment while under bias for 1,000 hours (IEC 68-2-1 Test Aa)
Temperature/Humidity Bias	+85°C/85% R.H. environment while under bias for 1,000 hours (JESD22-A101A-B)
Thermal Shock	100 cycles of air-air thermal shock from -40°C to +125°C with 15 minute soaks (IEC 68-2-4)
Tumble Test	300 Random Drops of Test Box on to Steel Base from 1.0m, 10 Tumbles/Minute
Vibration	16 minutes in each X, Y, Z axis from 20 to 2,000 Hz with peak acceleration of 20 G (MIL 883E, Method 2007.2,A)
Mechanical Shock	3 pulses of 10,000 G in each of the X, Y, and Z directions (IEC 68-2-27 Test Ea)
ESD-HBM	3 discharges of ±2kV direct contact to I/O pins (MIL 883E, Method 3015.7)
ESD-LID/GND	3 discharges of ±8kV direct contact to lid while unit is grounded (IEC 61000-4-2)
ESD-MM	3 discharges of ±200V direct contact to IO pins (ESD STM5.2)

Specification Revisions

Revision	Specification Changes	Date
A	Initial Release ECR#15-181	5/21/2015
В	Changed THD to .25% ECR#15-259	7/21/2015

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Model/Reference Number: Datasheet SPH1642HT5H-1 Rev B © Copyright 2015 Knowles Phone: (630) 250-5100 Fax: (630) 250-0575 sales@knowles.com

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